

### **General Description**

The WSD6036DN is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent R<sub>DSON</sub> and gate charge for most of the synchronous buck converter applications .

The WSD6040DN56 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

#### **Features**

Lead Fre e an d Green Devices Available

(RoH SCom plia nt)

100% UIS + Rg Tested

Reliable and Rugged

Moistu re Sensitivity Level MSL1

(per JED EC J-STD-020D)

### **Product Summery**

Bvdss	Rdson	ΙD
60V	12mΩ	50A

### **Applications**

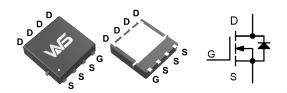
Secondary Side Synchronous Rectification

DC-DC Converter

Motor Control

Load Switching

## DFN3x3-8\_EP1 Pin Configuration



## Absolute Maximum Ratings $@T_A=25^{\circ}\mathbb{C}$ unless otherwise noted

Symbol	Parameter			Rating	Units
V <sub>DS</sub>	Drain-Source Voltage			60	V
V <sub>GS</sub>	Gate-Source Voltage			±20	V
ΙD	Continuous Drain Current $ Tc=25 $ $Tc=10 $		С	50	A
			°C	30	
I <sub>DM</sub> <sup>a</sup>	Pulsed Drain Current	Tc=25°C		90	A
P <sub>D</sub>	T <sub>C</sub> =		С	45	W
	Maximum Power Dissipation $Tc=1$	Tc=100	°C	18	] <sup>vv</sup>
Eas c	Single Pulse Avalanche Energy		L=0.1mH	39.2	mJ
Is	Diode Continuous Forward Current		Tc=25°C	50	A
TJ	Maximum Junction Temperature			150	$^{\circ}\!\mathbb{C}$
Tstg	Storage Temperature Range			-55 to 150	$^{\circ}$
R <sub>0</sub> JA <sup>b</sup>	Thermal Resistance Junction to ambient S		Steady State	62	°C/W
Rелс	Thermal Resistance-Junction to Case Steady State		3.3	°C/W	

Note a: Pulse width limited by max. junction temperature.

Note b: Surface Mounted on 1in2 pad area.

Note c: UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature Tj=25°C).



### Electrical Characteristics @T<sub>A</sub>=25℃ unless otherwise noted

Symbol	Parameter	Conditions		Min.	Тур.	Max.	Unit
Static							
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0V$ , $I_D = 250 \mu A$		60			V
Idss	Z C + W + D · C	$V_{DS}=48 \text{ V}, V_{GS}=0 \text{V}$				1	μА
	Zero Gate Voltage Drain Current	T <sub>J</sub> =85°C				30	
Igss	Gate Leakage Current	$V_{GS} = \pm 20V$ , V	$V_{\rm DS} = 0V$			±100	nA
On Characte	ristics						
V <sub>GS(TH)</sub>	Gate Threshold Voltage	$V_{GS}=V_{DS},I_{DS}=250\mu A$		1	1.6	2.5	V
D d	D : C O D : .	$V_{GS} = 10V, I_D = 25A$			14	17.5	mΩ
R <sub>DS(on)</sub> <sup>d</sup>	Drain-Source On-state Resistance	$V_{GS} = 4.5V$ , I		19	22	mΩ	
Switching							
Qg	Total Gate Charge	V <sub>DS</sub> =30V V <sub>GS</sub> =10V I <sub>D</sub> =25A			42		nC
Qgs	Gate-Sour Charge				6.4		nC
Qgd	Gate-Drain Charge				9.6		nC
td (on)	Turn-on Delay Time	$V_{\text{GEN}} = 10V$ $V_{\text{DD}} = 30V$ $I_{\text{D}} = 1A$ $R_{\text{G}} = 6\Omega$ $RL = 30\Omega$			17		ns
tr	Turn-on Rise Time				9		ns
td(off)	Turn-off Delay Time				58		ns
tf	Turn-off Fall Time				14		ns
Rg	Gat resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz			1.5		Ω
Dynamic							
Ciss	In Capacitance	V <sub>GS</sub> =0V V <sub>DS</sub> =30V f=1MHz			2100		pF
Coss	Out Capacitance				140		pF
Crss	Reverse Transfer Capacitance				100		pF
Drain-Source	Diode Characteristics and Maximum	Ratings					
Is	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current				18	A
Isм	Pulsed Source Current3					35	A
V <sub>SD</sub> <sup>d</sup>	Diode Forward Voltage	$I_{SD} = 20A$ , V	V <sub>GS</sub> =0V		0.8	1.3	V
trr	Reverse Recovery Time	- I <sub>SD</sub> =25A, dl <sub>SD</sub> /dt=100A/μs			27		ns
Qrr	Reverse Recovery Charge				33		nC

Note d: Pulse test; pulse width≤300µs, duty cycle≤2%.

Note e: Guaranteed by design, not subject to production testing.



## **Typical Operating Characteristics**

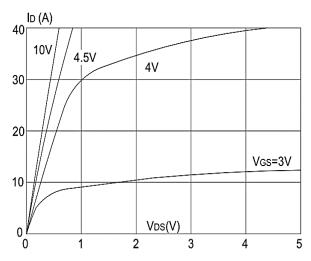


Figure1: Output Characteristics

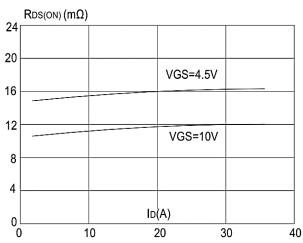
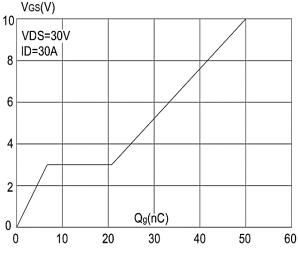
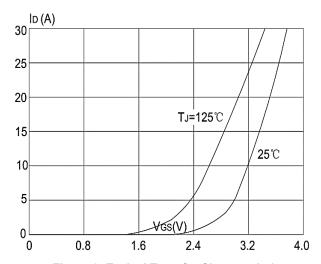


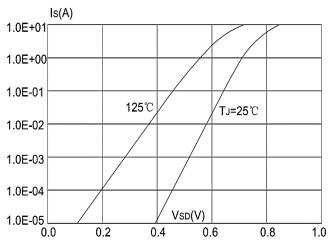
Figure 3:On-resistance vs. Drain Current



**Figure 5: Gate Charge Characteristics** 



**Figure 2: Typical Transfer Characteristics** 



**Figure 4: Body Diode Characteristics** 

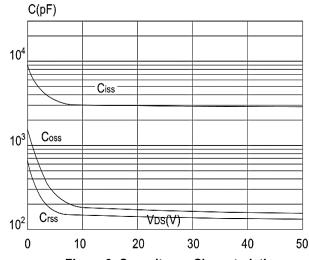


Figure 6: Capacitance Characteristics



# **Typical Operating Characteristics**

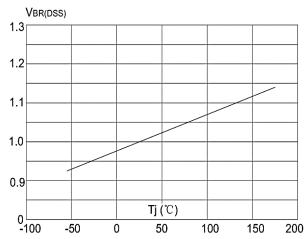


Figure 7: Normalized Breakdown Voltage vs Junction Temperature

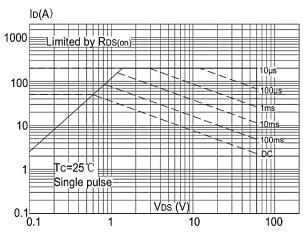


Figure 9: Maximum Safe Operating Area

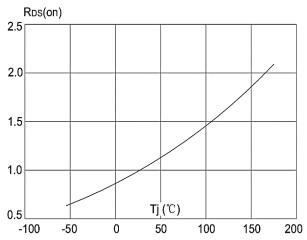


Figure 8: Normalized on Resistance vs.

Junction Temperature

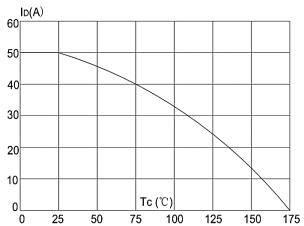


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

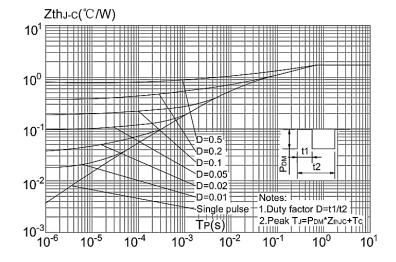


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambien



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